



### POWER DISSIPATION (DFN(PLP)2020-8)

This specification is at mounted on board. Power Dissipation ( $P_D$ ) depends on conditions of mounting on board.

This specification is based on the measurement at the condition below:

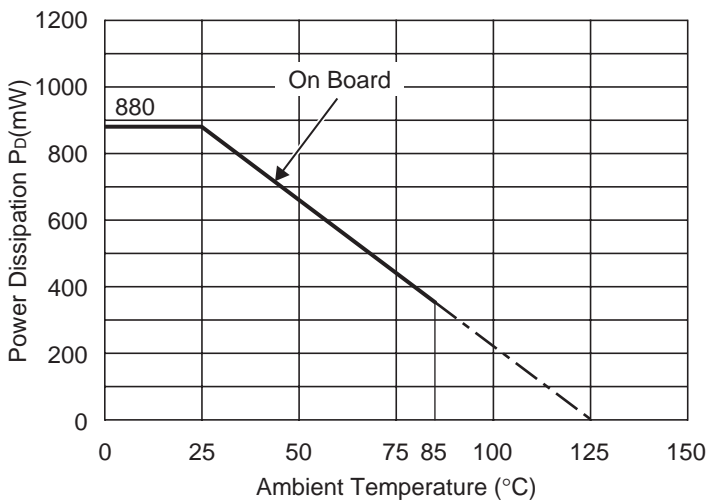
(Power Dissipation (DFN(PLP)2020-8) is substitution of DFN(PLP)1820-6.)

Measurement Conditions

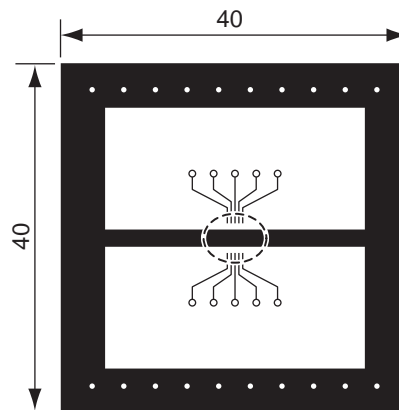
	Standard Land Pattern
Environment	Mounting on Board (Wind velocity=0m/s)
Board Material	Glass cloth epoxy plastic (Double sided)
Board Dimensions	40mm × 40mm × 1.6mm
Copper Ratio	Top side : Approx. 50% , Back side : Approx. 50%
Through-hole	φ0.54mm × 30pcs

Measurement Result (T<sub>opt</sub>=25°C, T<sub>jmax</sub>=125°C)

	Standard Land Pattern
Power Dissipation	880mW
Thermal Resistance	$\theta_{ja}=(125-25^\circ\text{C})/0.88\text{W}=114^\circ\text{C/W}$



Power Dissipation



Measurement Board Pattern

○ IC Mount Area Unit : mm

### RECOMMENDED LAND PATTERN

